

2A, 200V - 600V Surface Mount Super Fast Rectifiers

FEATURES

- Glass passivated junction chip
- Ideal for automated placement
- Low profile package
- Low power loss, high efficiency
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21



SMBF





MECHANICAF DATA

Case: SMBF

Molding compound: UL flammability classification rating 94V-0

Moisture sensitivity level: level 1, per J-STD-020

Packing code with suffix "G" means green compound (halogen-free) **Terminal:** Matte tin plated leads, solderable per JESD22-B102

Meet JESD 201 class 1A whisker test **Polarity:** Indicated by cathode band **Weight:** 0.101g (approximately)

PARAMETER	SYMBOL	CS (T _A =25°C unless otherwise noted) ES2DF ES2GF ES2JF			UNIT
Maximum repetitive peak reverse voltage	V _{RRM}	200	400	600	V
Maximum RMS voltage	V _{RMS}	140	280	420	V
Maximum DC blocking voltage	V _{DC}	200	400	600	V
Maximum average forward rectified current	$I_{F(AV)}$	2			А
Peak forward surge current, 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	50			А
Maximum instantaneous forward voltage (Note 1) @ 2 A	V _F	1.00	1.30	1.70	V
Maximum reverse current @ rated V_R T_J =25°C T_J =125°C	I _R -	10 350		μA	
Typical junction capacitance (Note 2)	CJ	10		pF	
Maximum reverse recovery time (Note 3)	t _{rr}	35			ns
Typical thermal resistance	R _{eJL} R _{eJA}	20 75			°C/W
Operating junction temperature range	T _J	- 55 to +150			°C
Storage temperature range	T _{STG}	- 55 to +150			°C

Note 1: Pulse test with PW=300µs, 1% duty cycle Note 2: Measured at 1 MHz and applied VR=4.0 V

Note 3: Test conditions: I_F =0.5A, I_R =1.0A, I_{RR} =0.25A



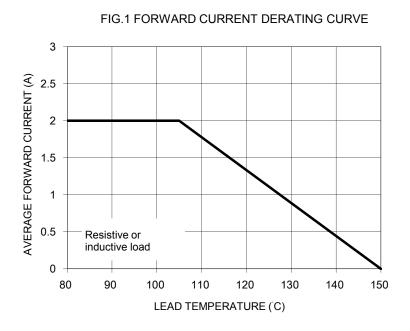
ORDERING INFORMATION					
PART NO.	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING	
ES2xF (Note 1, 2)	R4	G	SMBF	5,000 / 13" Paper reel	

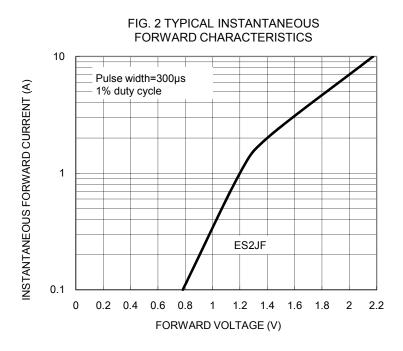
Note 1: "x" defines voltage from 200V (ES2DF) to 600V (ES2JF)

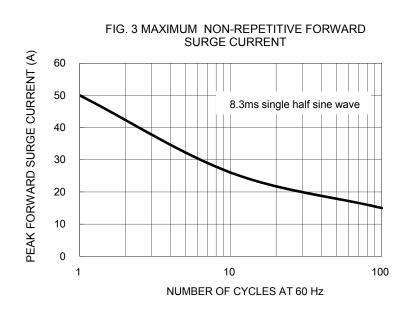
Note 2: Whole series with green compound

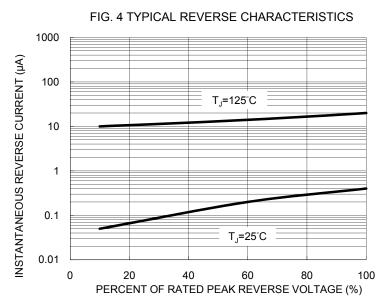
EXAMPLE					
EXAMPLE P/N	PART NO.	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION	
ES2DF R4G	ES2DF	R4	G	Green compound	

RATINGS AND CHARACTERISTICS CURVES (T_A=25°C unless otherwise noted)













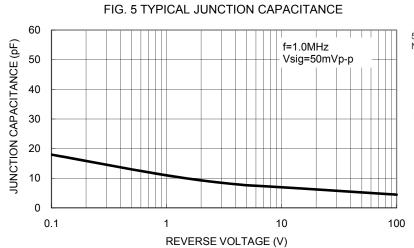
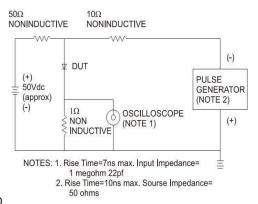
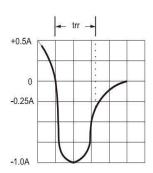


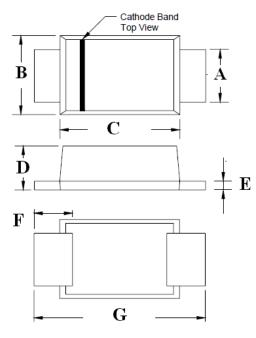
FIG.6 REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM





PACKAGE OUTLINE DIMENSIONS

SMBF



DIM.	Unit	(mm)	Unit (inch)		
DIWI.	Min	Max	Min	Max	
Α	1.90	2.61	0.075	0.103	
В	3.50	3.70	0.138	0.146	
С	4.20	4.75	0.165	0.187	
D	0.90	1.30	0.035	0.051	
E	0.18	0.26	0.007	0.010	
F	1.00		0.039		
G	5.10	5.50	0.201	0.217	

MARKING DIAGRAM



P/N = Specific Device Code G = Green compound Code

YW = Date Code F = Factory Code





Notice

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf, assumes no responsibility or liability for any errors or inaccuracies.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale.

Document Number: DS_D0000114 Version: A15